

## Surface Mount Solder Reflow Profile - PTVS Overvoltage Protectors

Surface Mount Packages are qualified by simulating the solder reflow conditions specified in IPC/JEDEC J-STD-020, which defines soldering conditions for moisture reflow sensitivity classification.

Users should ensure they do not exceed the scope of IPC/JEDEC J-STD-020 (Pb-Free) during solder assembly.

Profile Feature	Profile Limits
Preheat temperature min. ( $T_{smin}$ )	150°C
Preheat temperature max. ( $T_{smax}$ )	200°C
Ramp time ( $T_{smax} - T_{smin}$ )	60 – 120 seconds
Ramp –up rate ( $T_L$ to $T_p$ )	3 °C/second max
Liquidus temperature ( $T_L$ )	217°C
Time maintained above $T_L$	60-150 seconds
Peak package body temperature	245°C
Time within 5°C of peak temperature ( $t_p$ )	30 seconds max
Ramp –down rate ( $T_p$ to $T_L$ )	6 °C/second max
Time from 25°C to peak temperature	8 minutes max.

